



Product Change Notice

Micron PCN: 30650_AIMM
 Date: 3/23/2012

Type of Change:	Die Shrink, End of Life	
Title of Change:	50nm 2Gb DDR3 (V69A) EOL — AIMM	
Description of Change:	Micron's 50nm 2Gb DDR3 part is being replaced by parts being manufactured on the 30nm process node. This PCN includes Automotive temperature, Automotive grade Industrial temperature and Product Longevity Part (PLP) components.	
Reason for Change:	Optimization of Manufacturing Efficiency	
Contact Information:	<u>Marketing Contact</u> SVEN EVERS SEVERS@MICRON.COM Micron Semiconductor Prds	<u>Engineering Contact</u> STEVE DURNAL SDURNAL@MICRON.COM Micron Semiconductor Prds

Product Affected: All 50nm 2Gb DDR3 (V69A) automotive/industrial temperature grade parts and PLP parts

Affected Micron Part Numbers	Replacement Part Numbers
MT41J128M16HA-15E AAT:D	MT41K128M16JT-125 AAT:K
MT41J128M16HA-15E AIT:D	MT41K128M16JT-125 AIT:K
MT41J128M16HA-15E XIT:D	MT41K128M16JT-125 XIT:K
MT41J256M8HX-15E AAT:D	MT41K256M8DA-125 AAT:K
MT41J256M8HX-15E AIT:D	MT41K256M8DA-125 AIT:K

Method of Identification: Micron Part Number (see table above)

Micron Sites Affected: All Sites

Product/Data Availability

30nm Product:

*Sample Availability**: May 2012
Qual Data Availability: May 2012
Production Shipments: May 2012

50nm Product:

*Last Time Buy***: 31-May-2013
*Last Time Ship***: 30-May-2014

Qualification Plan:

Products manufactured on the 30nm process node will be qualified according to Micron's qualification procedures and best practices. Micron's Qualification Plan will be available upon request.

* Please contact factory for dates for your specific part numbers.

** Orders placed prior to the LTB date are subject to current inventory levels, which may vary based on market conditions and customer demand. Early orders are encouraged.